

Douglas DeVoto

List of Publications by Year in descending order

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13
papers

233
citations

1937685

4
h-index

2272923

4
g-index

13
all docs

13
docs citations

13
times ranked

228
citing authors

#	ARTICLE	IF	CITATIONS
1	A Comprehensive Review Toward the State-of-the-Art in Failure and Lifetime Predictions of Power Electronic Devices. IEEE Transactions on Power Electronics, 2019, 34, 4729-4746.	7.9	117
2	A Review of Degradation Behavior and Modeling of Capacitors. , 2018, , .		41
3	Transient Liquid Phase Bonding of AlN to AlSiC for Durable Power Electronic Packages. Advanced Engineering Materials, 2018, 20, 1800039.	3.5	16
4	Bond Wire Damage Detection and SOH Estimation of a Dual-Pack IGBT Power Module Using Active Power Cycling and Reflectometry. IEEE Transactions on Power Electronics, 2020, 35, 6761-6772.	7.9	16
5	Analysis and Optimization of a Multi-Layer Integrated Organic Substrate for High Current GaN HEMT-Based Power Module. , 2020, , .		12
6	Reliability of Bonded Interfaces for Automotive Power Electronics. , 2013, , .		9
7	Liquid-Cooled Aluminum Silicon Carbide Heat Sinks for Reliable Power Electronics Packages. Journal of Electronic Packaging, Transactions of the ASME, 2019, 141, .	1.8	9
8	Bond Wire Damage Detection and State of Health Estimation of a 1200V, 900A Dual Pack IGBT Power Module using the RL-Equivalent Circuit. , 2019, , .		6
9	Degradation Modeling and Reliability Assessment of Capacitors. , 2019, , .		3
10	Mechanical Characterization Study of Sintered Silver Pastes Bonded in a Double-Lap Configuration. , 2018, , .		2
11	Parametric Design Study of a Power Electronics Package for Improving Solder Joint Reliability. , 2020, , .		1
12	Thermal Assessment and In-Situ Monitoring of Insulated Gate Bipolar Transistors in Power Electronic Modules. , 2019, , .		1
13	Thermal Performance and Reliability of Large-Area Bonded Interfaces in Power Electronics Packages. , 2011, , .		0